

FLIP CLIP ATTACH AND COPPER CLIP ATTACH ON MOSFET DEVICE

ABSTRACT OF THE DISCLOSURE

A chip device including a leadframe that includes source and gate connections, a bumped die including solder bumps on a top side that is attached to the leadframe such that the solder bumps contact the source and gate connections, and a copper clip attached to the backside of the bumped die such that the copper clip contacts drain regions of the bumped die and a lead rail. The chip device is manufactured by flip chipping a bumped die onto the leadframe and placing the copper clip on a backside of the trench die such that the backside of the trench die is coupled to the lead rail. The process involves reflowing the solder bumps on the bumped die and solder paste that is placed between the copper clip and the backside of the bumped die.